

## IN THE SPECIFICATION

The paragraph beginning at page 1, line 21, is amended as follows:

Accordingly, there is a need for a connector system for high power, high performance ICs that reduces voltage drop [[droop]] and settling time and decouples or reduces noise interference to the IC.

The paragraph beginning at page 6, line 21 is amended as follows:

The connector assembly 10 is mounted to a bracket 230 and the bracket 230 is mounted to the inner frame 210. The tabs 22 and 24 (Figures 1A-1B) of the first and second conductive layers 12 and 14 forming the flex cable 18 are connected across a bank of capacitors 234 or “cap farm.” Each of the capacitors 238 of the bank of capacitors 234 is [[are]] mounted to a multiple level platform 240 and the platform 240 is attached to the inner frame 210. The bank of capacitors 234 is [[are]] connected at another end by another portion of the flex cable 18 to a power contact 242 and a ground contact 244 on the motherboard 202 (Figure 3). A compression contact 246 connects the other portion of the flex cable 232 to the power and ground contacts 242 and 244. As will be described in more detail below, the motherboard 202 may be connected to an external voltage or power supply 506 (Figure 5). The capacitors 238 are connected in parallel between the external power supply 606 and the CPU 112 or IC to condition the voltage or power to provide the large current transient (di/dt) required by some high power CPUs 112, such as the Itanium™ CPU as manufactured by Intel. The flex cable 232 and the bank of capacitors 234 should be capable of carrying at least 100 amperes of current. A cap farm cover assembly 248 may be positioned over the bank of capacitors 234 to protect the capacitors 238 from damage.